

WLCSP17_6-5-6

wafer level chip-size package; 17 bumps (6-5-6)

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP17
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	3-5-2012

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
A	seated height	0.56	-	0.61	0.66	mm
A ₂	package height	0.38	-	0.41	0.44	mm
n ₂	actual quantity of termination	-	-	17	-	

2. Package outline

Fig. 1. Package outline WLCSP17 (WLCSP17_6-5-6)



3. Legal information

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